



EuroForm 10

CONFORMABLE RELEASE FILM

EuroForm 12

CONFORMABLE RELEASE FILM

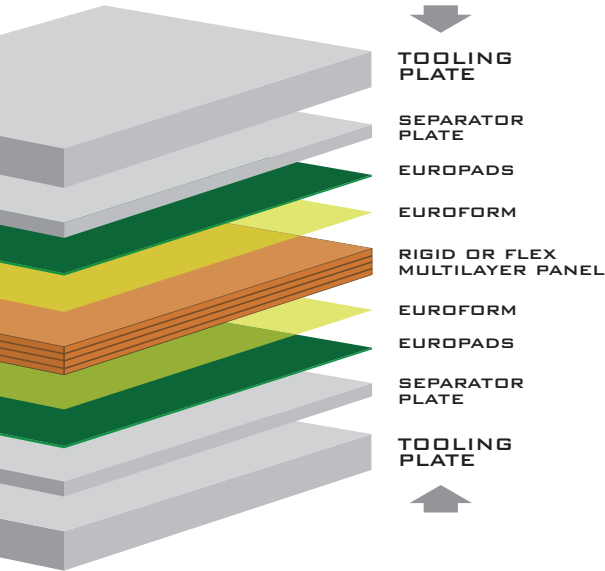
PROCESS PARAMETER

Temperature	up to 220 °C (428 °F)
Pressure	100 - 300 N/cm ² (10 - 30 bar)

STORAGE & HANDLING

Temperature	15 - 25 °C (59 - 77 °F)
Humidity	45 - 55%
Storage	Store flat in original packaging.

LAMINATION LAYUP EXAMPLE



PRODUCT DESCRIPTION

EuroForm family of highly conformable release films are designed for use in flexible and rigid-flex PCB fabrication. EuroForm is constructed of multiple layers, with a core that softens at temperature, allowing the conformable release sheet to adapt to the contours of the circuitry at pressure.

BENEFITS

EuroForm provides a hydraulic seal around the flexible circuit, promoting the resin flow and fill characteristics of the bond-ply and coverlay materials.

EuroForm conformable release films have proven beneficial in eliminating voids.

EuroForm conformable release films have a coating on both sides which releases from most surfaces.

EuroForm 12 can be utilized where greater Z-axis conformation may be required on heavier copper traces.

APPLICATIONS

EuroForm is used in the PCB manufacturing process for balancing height differences during flexible circuit board lamination and provides a consistent pressure distribution. Some examples of application:

- Laminating coverlays on flexible circuits
- Manufacturing flexible multi-layers with bond plies
- Manufacturing rigid-flex PCBs with standard, low flow prepreg

MATERIAL PROPERTIES

	EuroForm 10	EuroForm 12
Thickness	.010" (250 μm)	.012" (300 μm)
Density	0.95 g/cm ³	0.95 g/cm ³
Dimensional Stability	200 ppm/°C	200 ppm/°C
Softening Point	approx. 135 °C (275 °F)	
Color	White Translucent	White
Temperature Resistance	≤ 220 °C (428 °F)	≤ 220 °C (428 °F)
Elongation	TBA	250%

AVAILABILITY

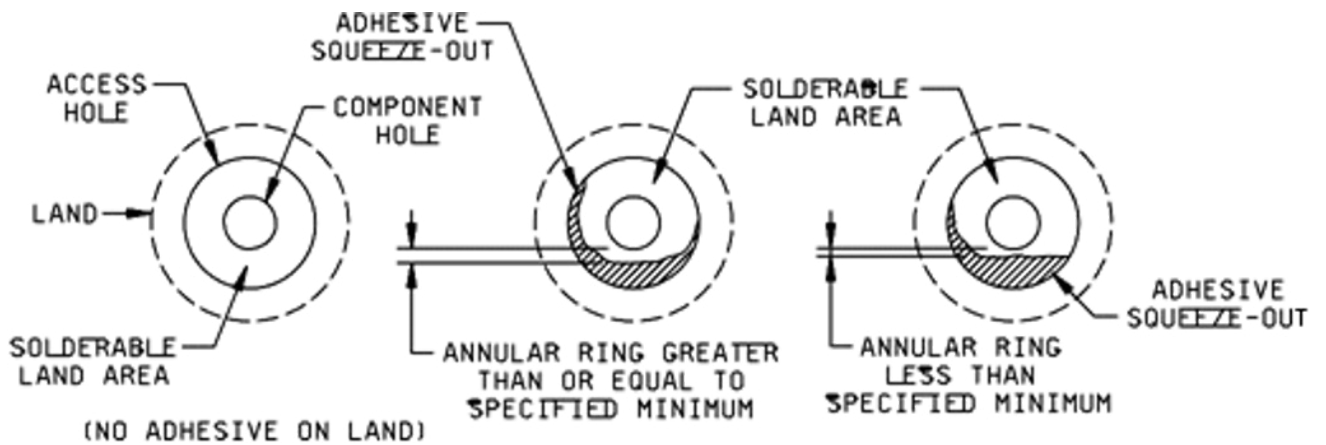
Available in custom sheet sizes. Can be tooled and punched according to your specifications.



RESULTS

EuroForm 12 Conformable Release Film produces unmatched results in controlling excessive adhesive flow in your flexible circuit lamination process. Pristine results in controlling adhesive flow on lands with superb annular ring.

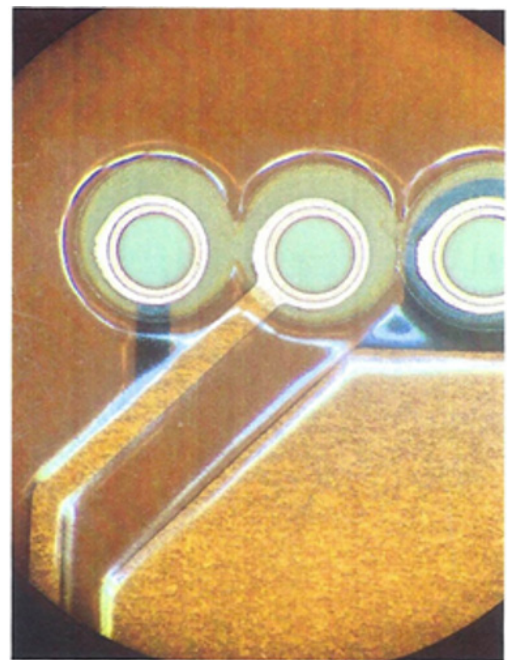
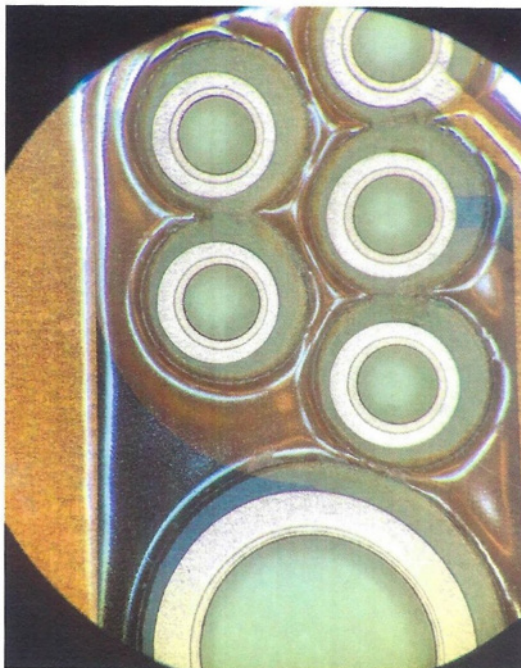
MIL-P-50884E



DESIRED

ACCEPTABLE

NOT ACCEPTABLE



EuroForm 12 creates desired results. Desired control of adhesive squeeze out when you use EuroForm 12.